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PCB VHDCI breakout rev1.1

8x Extension boards

UPPER VHDCI

LVDS1
J40

LVDS2
J41

LVDS3
J42

LVDS4
J43

LVDS8
J48

LVDS7
J47

LOWER VHDCI

LVDS6
J46

LVDS5
J45

To METLINO

J2

IC33

IC35

IC36

MP1
GND
MP2
GND

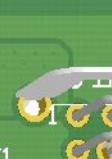
LD2

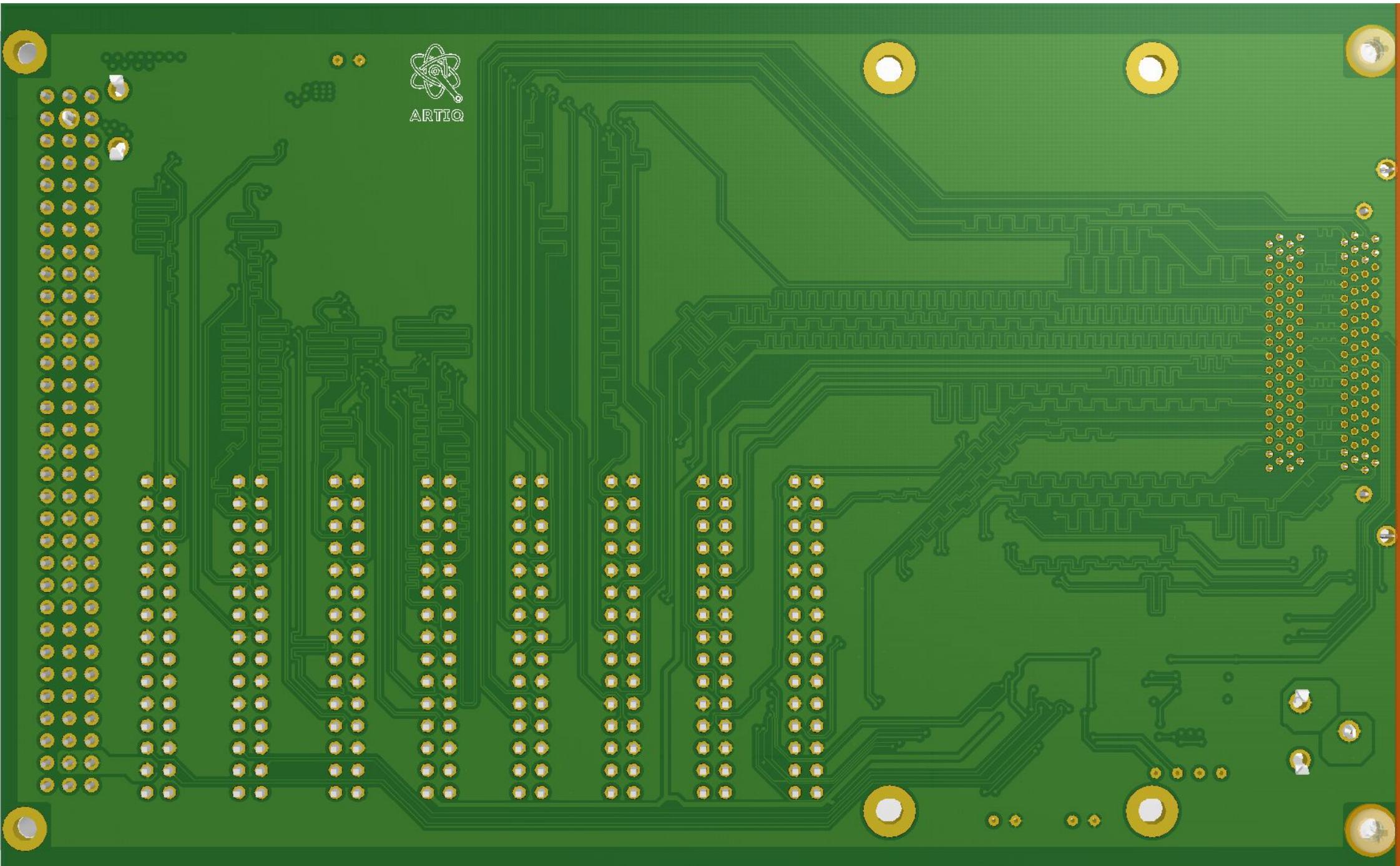
MP1

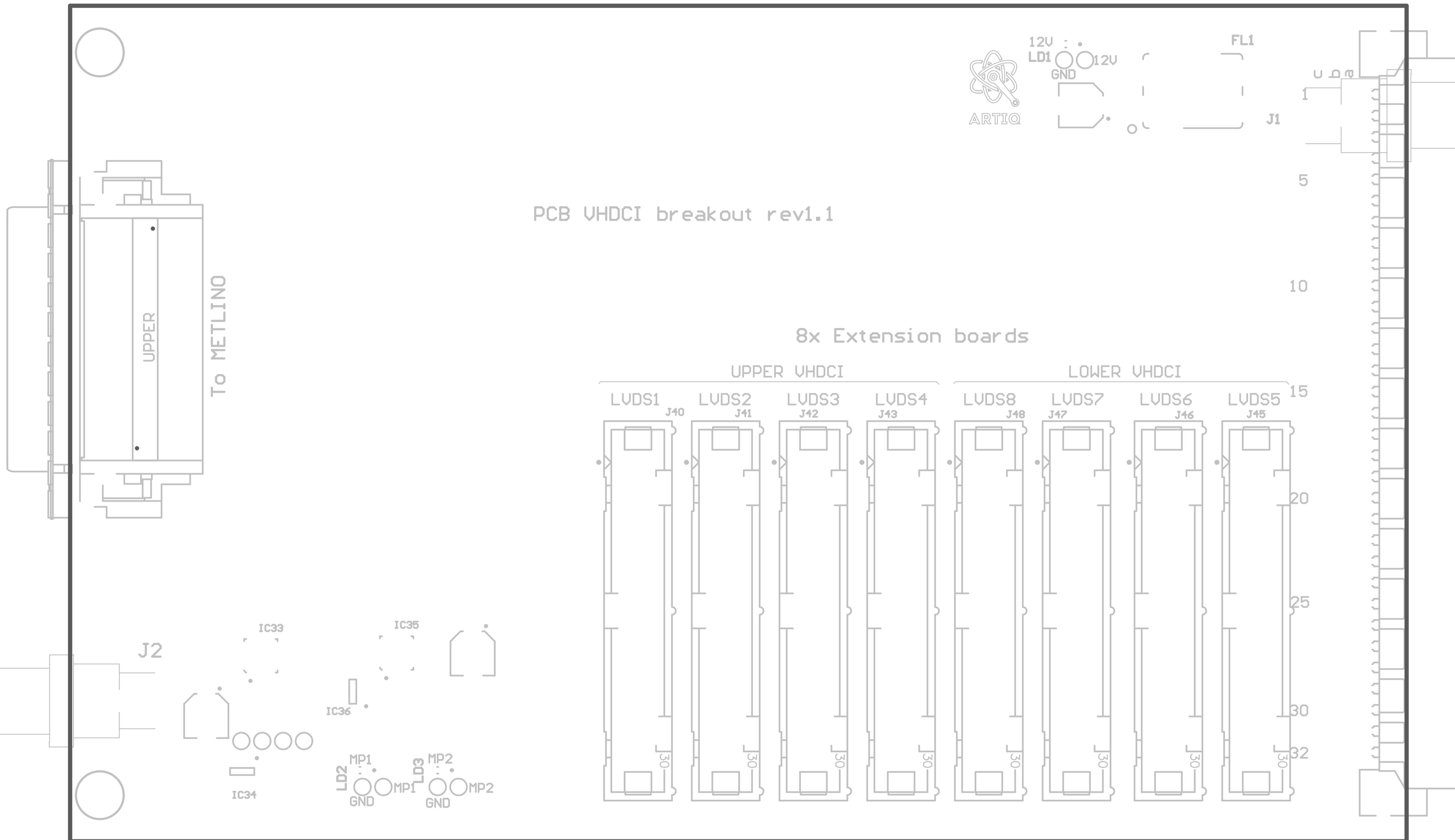
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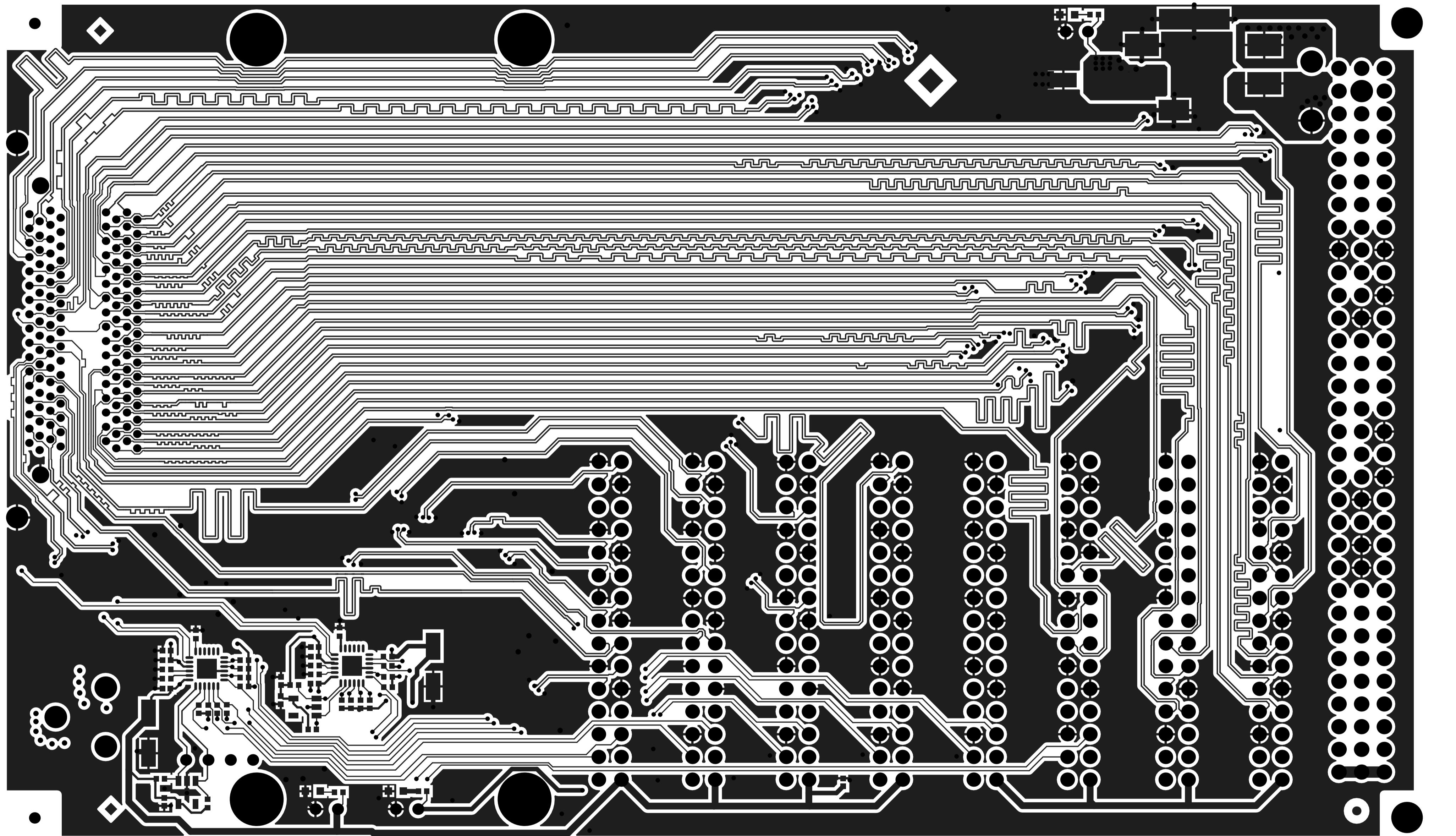
MP2

IC34

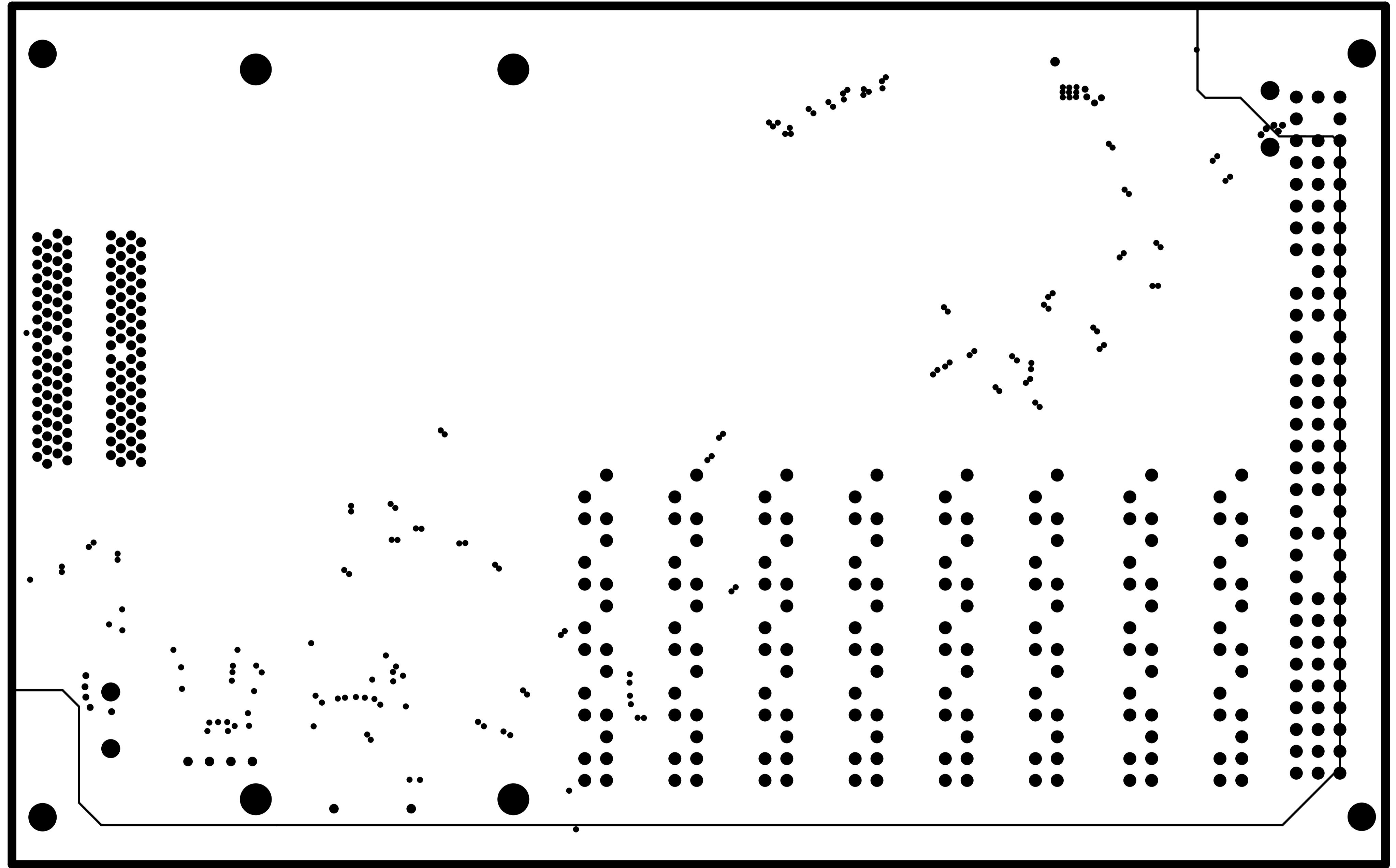


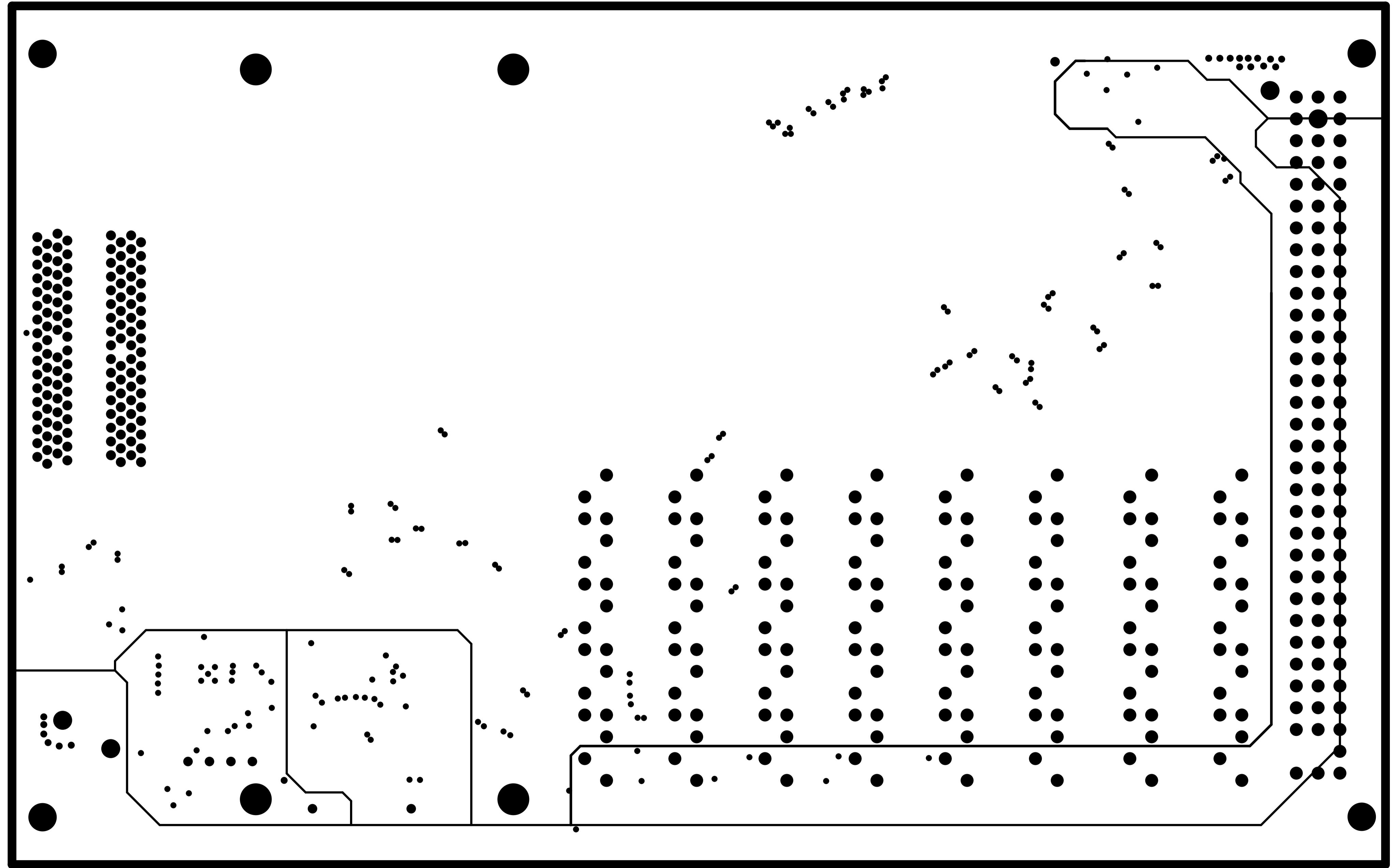


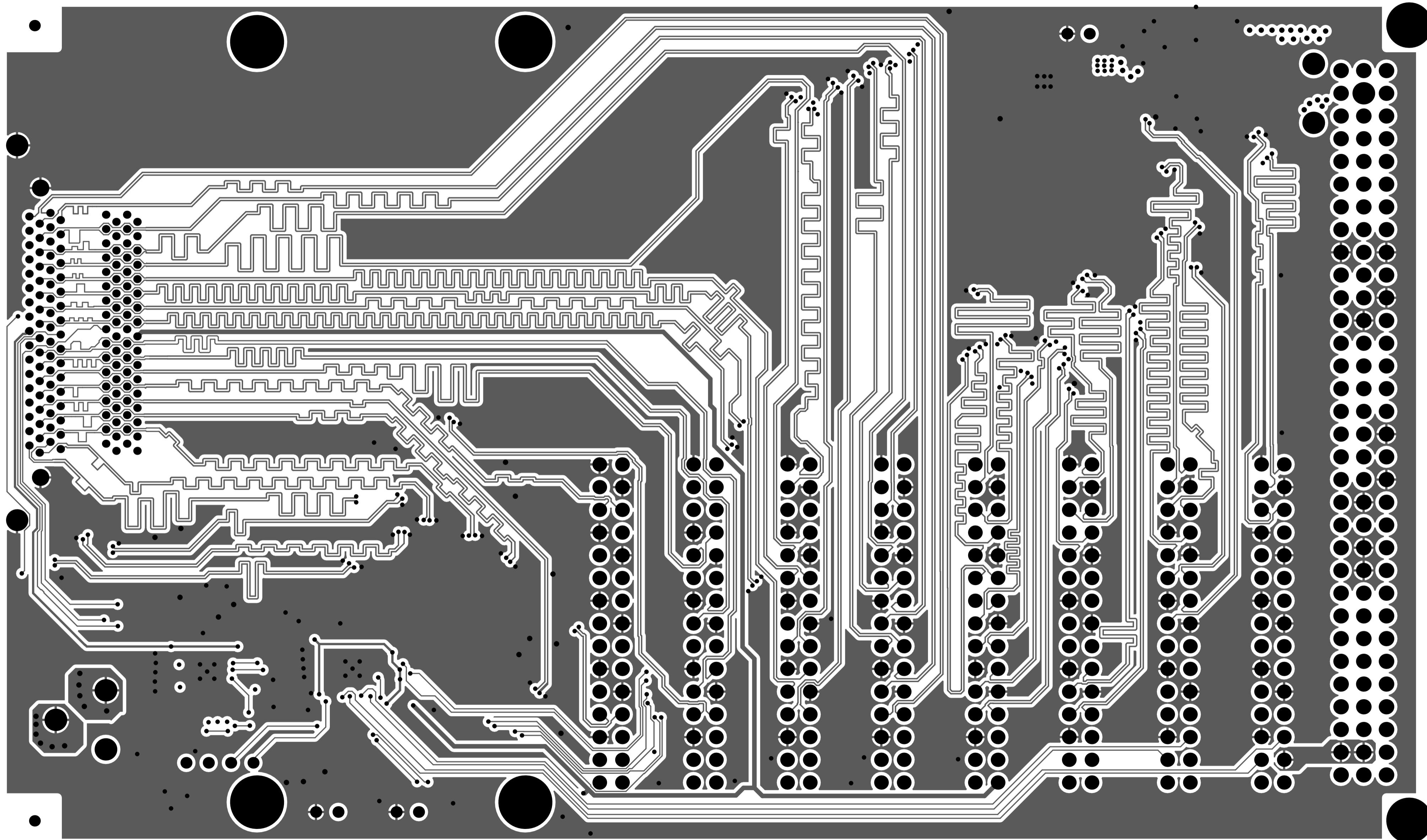


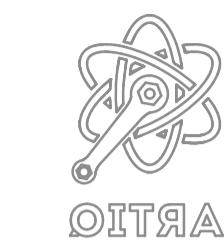


Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	TopOverlay				
2	TopSolder	Solder Resist	0.40mil	4.5	
3	TopLayer	Copper	2.21mil		
4	Dielectric1	FR-4	7.09mil	4.5	
5	Internal Plane 1	Copper	1.38mil		
6	Dielectric 10		42.52mil	4.5	
7	Internal Plane 2	Copper	1.38mil		
8	Dielectric9	FR-4	7.09mil	4.5	
9	BottomLayer	Copper	2.21mil		
10	BottomSolder	Solder Resist	0.40mil	4.5	
11	BottomOverlay				









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